

2713751

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Set, consisting of orthogonal PCB terminal blocks for 6 x 4 positions (24-pos.), color: light gray



Your advantages

- · Maintenance-free and vibration-resistant, thanks to the Reakdyn principle or spring-loaded elements
- · PCB terminal block is orthogonal to the PCB
- · Internationally recognized and proven screw connection

Commercial data

Item number	2713751
Packing unit	1 pc
Minimum order quantity	1 pc
Sales key	AC08
Product key	ACHADA
GTIN	4017918914479
Weight per piece (including packing)	49.3 g
Weight per piece (excluding packing)	49.5 g
Customs tariff number	85369010
Country of origin	DE



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Set consists of

MKDSO 2,5/4-L KMGY - PCB terminal block

2908485

https://www.phoenixcontact.com/us/products/2908485



Printed circuit board terminal, nominal current: 24 A, rated voltage (III/2): 400 V, nominal cross section: 2.5 mm^2 , number of potentials: 4, number of rows: 1, number of positions per row: 4, product range: MKDSO 2,5/..-L, pitch: 5 mm, connection method: Screw connection with tension sleeve, mounting: Wave soldering, conductor/PCB connection direction: 0 °, color: light gray, Pin layout: Linear pinning, Solder pin [P]: 3.5 mm, number of solder pins per potential: 1, type of packaging: packed in cardboard. Product with pin output on left side

MKDSO 2,5/4-R KMGY - PCB terminal block

2908472

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Printed circuit board terminal, nominal current: 24 A, rated voltage (III/2): 400 V, nominal cross section: 2.5 mm², number of potentials: 4, number of rows: 1, number of positions per row: 4, product range: MKDSO 2,5/..-R, pitch: 5 mm, connection method: Screw connection with tension sleeve, mounting: Wave soldering, conductor/PCB connection direction: 0 °, color: light gray, Pin layout: Linear pinning, Solder pin [P]: 3.5 mm, number of solder pins per potential: 1, type of packaging: packed in cardboard. Product with pin output on right side



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Technical data

Product properties

Product type	Printed circuit board terminal
Product family	MKDSO 2,5/L+R
Product line	COMBICON Terminals M
Number of positions	4
Pitch	5 mm
Number of connections	4
Number of rows	1
Number of potentials	4
Pin layout	Linear pinning
Solder pins per potential	1

Electrical properties

Properties

Nominal current I _N	24 A
Nominal voltage U _N	400 V
Rated voltage (III/3)	250 V
Rated surge voltage (III/3)	4 kV
Rated voltage (III/2)	400 V
Rated surge voltage (III/2)	4 kV
Rated voltage (II/2)	630 V
Rated surge voltage (II/2)	4 kV

Connection data

Connection technology

Nominal cross section	2.5 mm ²
Conductor connection	
Connection method	Screw connection with tension sleeve
Conductor cross section rigid	0.14 mm² 2.5 mm²
Conductor cross section flexible	0.14 mm² 2.5 mm²
Conductor cross section AWG	26 14
Conductor cross section flexible, with ferrule without plastic sleeve	0.25 mm² 2.5 mm²
Conductor cross section, flexible, with ferrule, with plastic sleeve	0.25 mm² 2.5 mm²
2 conductors with same cross section, solid	0.14 mm² 0.75 mm²
2 conductors with same cross section, flexible	0.14 mm² 0.75 mm²
2 conductors with same cross section, flexible, with ferrule without plastic sleeve	0.25 mm ² 0.75 mm ²
2 conductors with the same cross section, flexible, with TWIN ferrule with plastic sleeve	0.5 mm ² 1.5 mm ²
Stripping length	8 mm



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Tightening torque	0.5 Nm 0.6 Nm
ounting	
Mounting type	Wave soldering
Pin layout	Linear pinning
aterial specifications	
Material data - contact	
Note	WEEE/RoHS-compliant, free of whiskers according to IEC 60068-2-82/JEDEC JESD 201
Contact material	Cu alloy
Surface characteristics	Tin-plated
Metal surface terminal point (top layer)	Tin (5 - 7 µm Sn)
Metal surface terminal point (middle layer)	Nickel (2 - 3 µm Ni)
Metal surface soldering area (top layer)	Tin (5 - 7 µm Sn)
Metal surface soldering area (middle layer)	Nickel (2 - 3 µm Ni)
Meterial data haveing	
Material data - housing Color (Housing)	light gray (7035)
Insulating material	light gray (7035) PA
Insulating material group	1
CTI according to IEC 60112	600
Flammability rating according to UL 94	VO
Glow wire flammability index GWFI according to EN 60695-2-12	850
Glow wire ignition temperature GWIT according to EN 60695-2- 13	775
Temperature for the ball pressure test according to EN 60695-10-2	125 °C
otes	
Note on application	For reliable conductor connection, always adhere to a defined tightening torque. During conductor connection (mounting), the terminal blocks must be supported (held with one hand, support on the housing).
imensions	
Dimensional drawing	h p
Pitch	5 mm
Width [w]	10.95 mm
Height [h]	18.05 mm
Length [I]	15.3 mm



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Solder pin length [P]	3.5 mm
Pin dimensions	0.8 x 1 mm
PCB design	
Hole diameter	1.4 mm
echanical tests	
Test for conductor damage and slackening	JEO 00000 4 4000 44
Specification	IEC 60999-1:1999-11
Result	Test passed
Pull-out test	
Specification	IEC 60999-1:1999-11
Conductor cross section/conductor type/tractive force	0.14 mm² / solid / > 10 N
setpoint/actual value	0.14 mm² / flexible / > 10 N
	2.5 mm² / solid / > 50 N
	2.5 mm² / flexible / > 50 N
Temperature-rise test Specification	IEC 60947-7-4:2019-01
	IEC 60947-7-4:2019-01
	The sum of ambient temperature and temperature rise of the
Specification	
Specification	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting
Specification Requirement temperature-rise test	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting
Specification Requirement temperature-rise test Short-time withstand current	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature.
Specification Requirement temperature-rise test Short-time withstand current Specification	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature.
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification Insulating material group	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ IEC 60664-1:2007-04
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ IEC 60664-1:2007-04 I CTI 600
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112) Rated insulation voltage (III/3)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ IEC 60664-1:2007-04 I CTI 600 250 V
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112) Rated insulation voltage (III/3) Rated surge voltage (III/3)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ IEC 60664-1:2007-04 I CTI 600 250 V 4 kV
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112) Rated insulation voltage (III/3) Rated surge voltage (III/3) minimum clearance value - non-homogenous field (III/3)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ IEC 60664-1:2007-04 I CTI 600 250 V 4 kV 3 mm
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112) Rated insulation voltage (III/3) Rated surge voltage (III/3) minimum clearance value - non-homogenous field (III/3) minimum creepage distance (III/3)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ IEC 60664-1:2007-04 I CTI 600 250 V 4 kV 3 mm 3.2 mm
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112) Rated insulation voltage (III/3) Rated surge voltage (III/3) minimum clearance value - non-homogenous field (III/3) minimum creepage distance (III/3) Rated insulation voltage (III/2)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ IEC 60664-1:2007-04 I CTI 600 250 V 4 kV 3 mm 3.2 mm 400 V
Specification Requirement temperature-rise test Short-time withstand current Specification Insulation resistance Specification Insulation resistance, neighboring positions Air clearances and creepage distances Specification Insulating material group Comparative tracking index (IEC 60112) Rated insulation voltage (III/3) Rated surge voltage (III/3) minimum creepage distance (III/3) Rated insulation voltage (III/3) Rated insulation voltage (III/2) Rated surge voltage (III/2)	The sum of ambient temperature and temperature rise of the PCB terminal block shall not exceed the upper limiting temperature. IEC 60947-7-4:2019-01 IEC 60512-3-1:2002-02 > 5 MΩ IEC 60664-1:2007-04 I CTI 600 250 V 4 kV 3 mm 3.2 mm 400 V 4 kV

4 kV

Rated surge voltage (II/2)



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minimum clearance value - non-homogenous field (II/2)	3 mm
minimum creepage distance (II/2)	3.2 mm
ironmental and real-life conditions	
oration test	
Specification	IEC 60068-2-6:2007-12
Frequency	10 - 150 - 10 Hz
Sweep speed	1 octave/min
Amplitude	0.35 mm (10 Hz 60.1 Hz)
Acceleration	5g (60.1 Hz 150 Hz)
Test duration per axis	2.5 h
Test directions	X-, Y- and Z-axis
ow-wire test	
Specification	IEC 60695-2-10:2013-04
Temperature	850 °C
Time of exposure	5 s
ging	
Specification	IEC 60947-7-4:2019-01
	2 112 11 1 112 11 21
nbient conditions	
Ambient temperature (operation)	-40 °C 105 °C (Depending on the current carrying capacity/derating curve)
Ambient temperature (storage/transport)	-40 °C 55 °C
Relative humidity (storage/transport)	30 % 70 %

Packaging specifications

Ambient temperature (assembly)

Type of packaging	nacked in cardboard
Type of packaging	packed in caraboard

-5 °C ... 100 °C

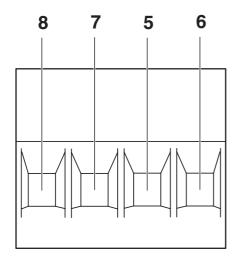


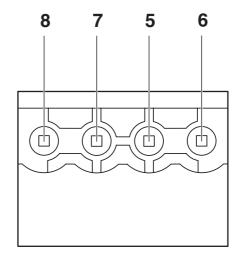
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Drawings

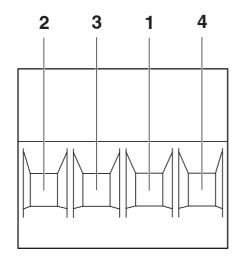
Schematic diagram

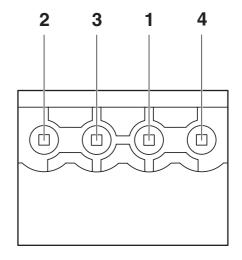




Pin assignment right

Schematic diagram



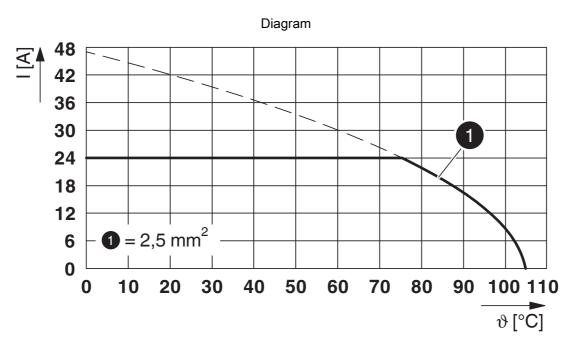


Pin assignment left



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Type: MKDSO 2,5/...-L



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Approvals

To download certificates, visit the product detail page: https://www.phoenixcontact.com/us/products/2713751

CSA Approval ID: 13631				
	Nominal voltage U_N	Nominal current I _N	Cross section AWG	Cross section mm ²
Use group B				
	300 V	10 A	28 - 12	-
Use group D				
	300 V	10 A	28 - 12	-

cULus F Approval II	cULus Recognized Approval ID: E60425-19770427			
	Nominal voltage U _N	Nominal current I _N	Cross section AWG	Cross section mm ²
Use group B				
	300 V	20 A	30 - 12	-

₹	VDE report with production monitoring Approval ID: 40023968				
		Nominal voltage U _N	Nominal current I _N	Cross section AWG	Cross section mm ²
		450 V	24 A	-	0.2 - 2.5



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Classifications

ECLASS

	ECLASS-13.0	27460101	
	ECLASS-15.0	27460101	
ETIM			
	ETIM 9.0	EC002643	
U	NSPSC		
	UNSPSC 21.0	39121400	



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Environmental product compliance

EU RoHS

Fulfills EU RoHS substance requirements	Yes, No exemptions
China RoHS	
Environment friendly use period (EFUP)	EFUP-50
	An article-related China RoHS declaration table can be found in the download area for the respective article under "Manufacturer declaration". For all articles with EFUP-E, no China RoHS declaration table issued and required.
EU REACH SVHC	
REACH candidate substance (CAS No.)	No substance above 0.1 wt%
EF3.0 Climate Change	
CO2e kg	0.185 kg CO2e

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